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### **Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5ffn1020i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5ffn1020i</a>

### Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as shown in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

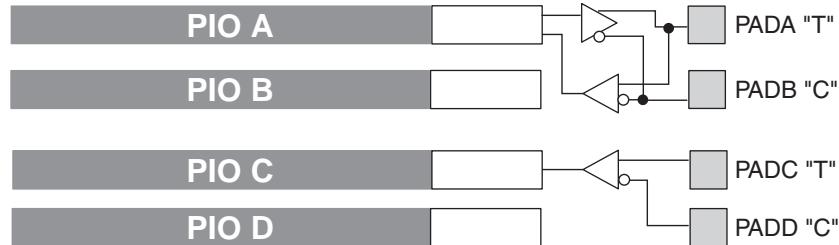
The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

high-speed interfaces in the LatticeSC devices. Figure 2-18 shows how differential receivers and drivers are arranged between PIOs.

**Figure 2-18. Differential Drivers and Receivers**



\*Differential Driver only available on right and left of the device.

## PIO

The PIO contains five blocks: an input register block, output register block, tristate register block, update block, and a control logic block. These blocks contain registers for both single data rate (SDR), double data rate (DDR), and shift register operation along with the necessary clock and selection logic.

### Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 show the diagram of the input register block. The signal from the PURE-SPEED I/O buffer (DI) enters the input register block and can be used for three purposes, as a source for the combinatorial (INDD) and clock outputs (INCK), the input into the SDR register/latch block and the input to the delay block. The output of the delay block can be used as combinatorial (INDD) and clock (INCK) outputs, an input to the DDR/Shift Register Block or an input into the SDR register block.

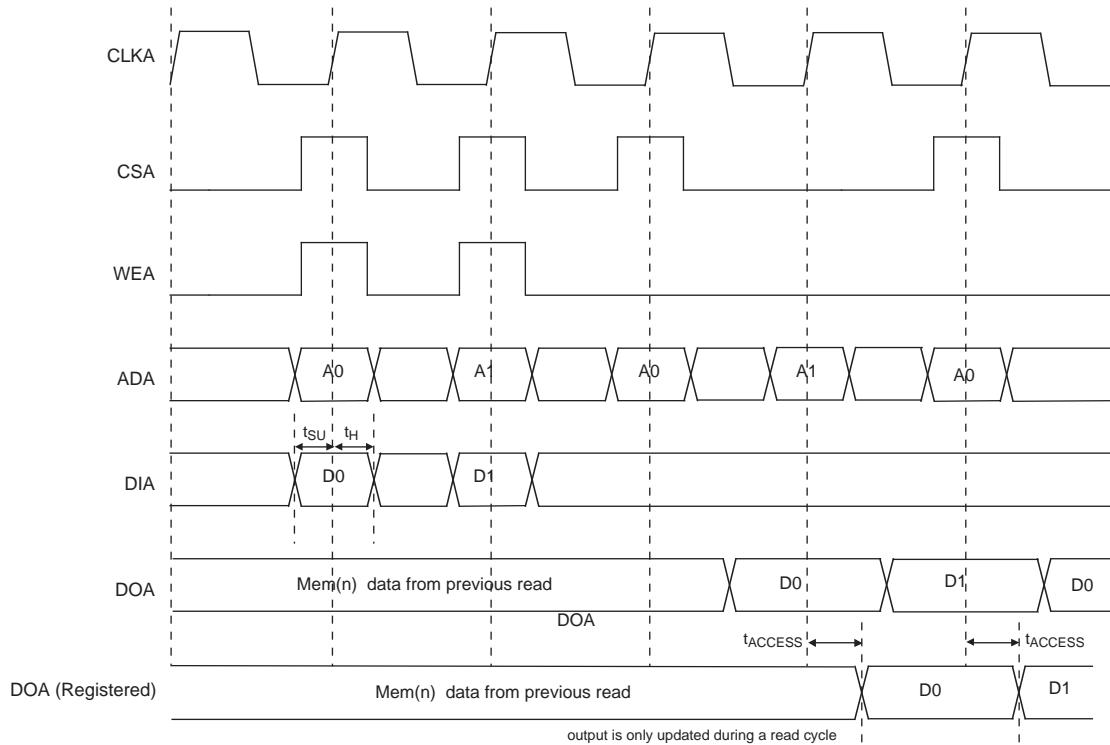
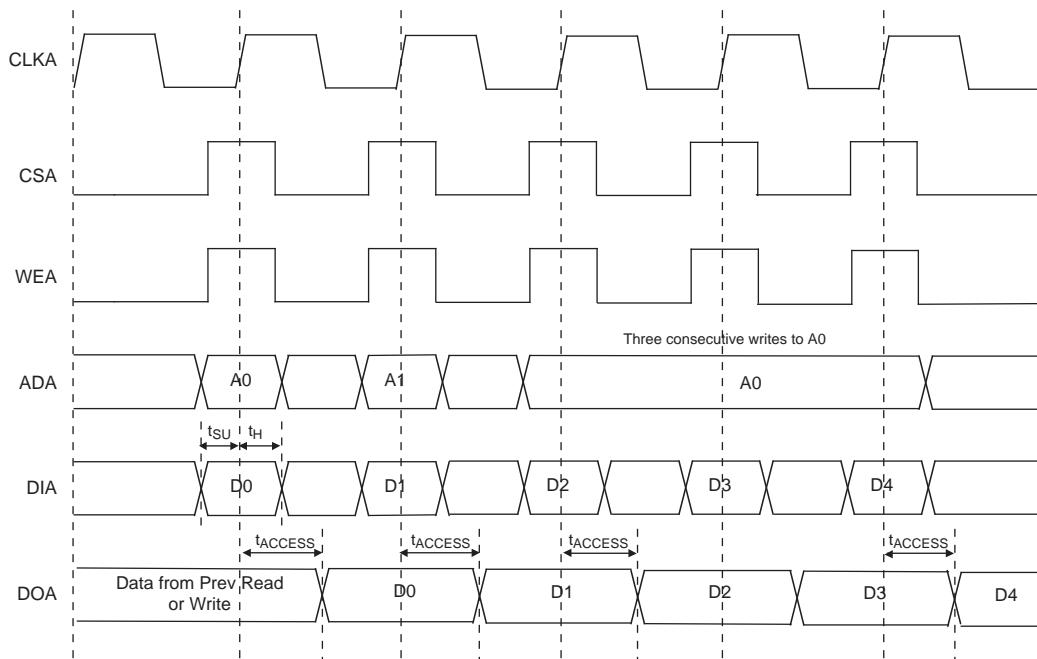
### Input SDR Register/Latch Block

The SDR register/latch block has a latch and a register/latch that can be used in a variety of combinations to provide a registered or latched output (INFF). The latch operates off high-speed input clocks and latches data on the positive going edge. The register/latch operates off the low-speed input clock and registers/latches data on the positive going edge. Both the latch and the register/latch have a clock enable input that is driven by the input clock enable. In addition both have a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR (LSR has precedence over CE) and Global Set Reset GSR enable or disable. The register and latch LSR inputs are driven from LSRI, which is generated from the PIO control MUX. The GSR inputs are driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

### Input Delay Block

The delay block uses 144 tapped delay lines to obtain coarse and fine delay resolution. These delays can be adjusted during configuration or automatically via DLL or AIL blocks. The Adaptive Input Logic (AIL) uses this delay block to adjust automatically the delay in the data path to ensure that it has sufficient setup and hold time.

The delay line in this block matches the delay line that is used in the 12 on-chip DLLs. The delay line can be set via configuration bits or driven from a calibration bus that allows the setting to be controlled either from one of the on-chip DLLs or user logic. Controlling the delay from one of the on-chip DLLs allow the delay to be calibrated to the DLL clock and hence compensated for the variations in process, voltage and temperature.

**Figure 3-8. Read Mode with Input and Output Registers****Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)**

Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

**Signal Descriptions (Cont.)**

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
<b>Multi-chip Alignment (User I/O if not used.)</b>		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip)
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
<b>Miscellaneous Dedicated Pins</b>		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
<b>SERDES Block (Dedicated Pins)</b>		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.











**LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA<sup>1,2</sup> (Cont.)**

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).

2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AJ34	PL98A	6	
AK34	PL98B	6	
AB27	PL98C	6	
AC27	PL98D	6	
AF33	PL99A	6	
AG33	PL99B	6	
AC29	PL99C	6	
AD29	PL99D	6	
AE31	PL103A	6	
AF31	PL103B	6	
AF30	PL103C	6	
AF29	PL103D	6	
AH33	PL104A	6	
AJ33	PL104B	6	
AC28	PL104C	6	
AD28	PL104D	6	
AH32	PL107A	6	
AJ32	PL107B	6	
AD27	PL107C	6	
AE27	PL107D	6	VREF2_6
AG34	PL109A	6	
AH34	PL109B	6	
AC26	PL109C	6	
AB26	PL109D	6	
AK33	PL112A	6	
AL33	PL112B	6	
AG30	PL112C	6	
AH30	PL112D	6	
AL34	PL115A	6	
AM34	PL115B	6	
AJ30	PL115C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL115D	6	LLC_DLCC_IN_E/LLC_DLCC_FB_F
AJ31	PL116A	6	
AH31	PL116B	6	
AD26	PL116C	6	
AD25	PL116D	6	
AL32	PL117A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL117B	6	LLC_DLCC_IN_F/LLC_DLCC_FB_E
AG29	PL117C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL117D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-	
AF27	TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F6	A_VDDOB0_R	-	
B4	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
F7	A_VDDOB1_R	-	
B5	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
E6	VCC12	-	
A5	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B6	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
A6	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
C6	VCC12	-	
D4	A_VDDIB1_R	-	
C7	VCC12	-	
D5	A_VDDIB2_R	-	
A7	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B7	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E7	VCC12	-	
A8	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
F8	A_VDDOB2_R	-	
B8	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
F9	A_VDDOB3_R	-	
B9	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
E8	VCC12	-	
A9	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B10	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
A10	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
C10	VCC12	-	
D6	A_VDDIB3_R	-	
G10	VCC12	-	
D7	B_VDDIB0_R	-	
E10	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
F10	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
K10	VCC12	-	
A11	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D10	B_VDDOB0_R	-	
B11	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D11	B_VDDOB1_R	-	
B12	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L10	VCC12	-	
A12	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
F11	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
E11	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
G11	VCC12	-	
D8	B_VDDIB1_R	-	
G12	VCC12	-	

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
H34	PL40B	7	
M32	PL53A	7	
N32	PL53B	7	
P28	PL53C	7	
R28	PL53D	7	
J34	PL55A	7	
K34	PL55B	7	
P30	PL55C	7	
R30	PL55D	7	
W34	PL73A	6	
Y34	PL73B	6	
W32	PL75A	6	
Y32	PL75B	6	
AA34	PL78A	6	
AB34	PL78B	6	
AC34	PL81A	6	
AD34	PL81B	6	
Y30	PL82A	6	
AA30	PL82B	6	
AB33	PL83A	6	
AC33	PL83B	6	
AC2	PR83B	3	
AB2	PR83A	3	
AA5	PR82B	3	
Y5	PR82A	3	
AD1	PR81B	3	
AC1	PR81A	3	
AB1	PR78B	3	
AA1	PR78A	3	
Y3	PR75B	3	
W3	PR75A	3	
Y1	PR73B	3	
W1	PR73A	3	
R5	PR55D	2	
P5	PR55C	2	
K1	PR55B	2	
J1	PR55A	2	
R7	PR53D	2	
P7	PR53C	2	
N3	PR53B	2	
M3	PR53A	2	
H1	PR40B	2	
G1	PR40A	2	

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AH16	VCCIO4	-	
AJ13	VCCIO4	-	
AJ7	VCCIO4	-	
AL14	VCCIO4	-	
AL8	VCCIO4	-	
AM11	VCCIO4	-	
AM17	VCCIO4	-	
AM5	VCCIO4	-	
AE20	VCCIO5	-	
AE23	VCCIO5	-	
AE26	VCCIO5	-	
AH22	VCCIO5	-	
AH28	VCCIO5	-	
AJ19	VCCIO5	-	
AJ25	VCCIO5	-	
AL18	VCCIO5	-	
AL24	VCCIO5	-	
AL30	VCCIO5	-	
AM21	VCCIO5	-	
AM27	VCCIO5	-	
AA31	VCCIO6	-	
AB29	VCCIO6	-	
AC24	VCCIO6	-	
AD32	VCCIO6	-	
AE28	VCCIO6	-	
AG31	VCCIO6	-	
AK32	VCCIO6	-	
T29	VCCIO6	-	
U31	VCCIO6	-	
V32	VCCIO6	-	
W28	VCCIO6	-	
Y26	VCCIO6	-	
E31	VCCIO7	-	
G28	VCCIO7	-	
H32	VCCIO7	-	
K29	VCCIO7	-	
L31	VCCIO7	-	
M25	VCCIO7	-	
N28	VCCIO7	-	
P32	VCCIO7	-	
R25	VCCIO7	-	
J25	VCCIO1	-	
N11	VTT_2	2	

**LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA<sup>1,2</sup> (Cont.)**

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD33	PL59D	6		PL73D	6	
AA38	PL60A	6		PL74A	6	
AB38	PL60B	6		PL74B	6	
AC29	PL60C	6		PL74C	6	
AD29	PL60D	6		PL74D	6	
AA41	PL61A	6		PL75A	6	
AB41	PL61B	6		PL75B	6	
AC34	PL61C	6		PL75C	6	
AD34	PL61D	6		PL75D	6	
AA42	PL63A	6		PL77A	6	
AB42	PL63B	6		PL77B	6	
AC37	PL63C	6		PL77C	6	
AD37	PL63D	6		PL77D	6	
AC38	PL64A	6		PL78A	6	
AD38	PL64B	6		PL78B	6	
AD36	PL64C	6		PL78C	6	
AE36	PL64D	6		PL78D	6	
AC39	PL65A	6		PL79A	6	
AD39	PL65B	6		PL79B	6	
AD35	PL65C	6		PL79C	6	
AE35	PL65D	6		PL79D	6	
AC40	PL67A	6		PL81A	6	
AD40	PL67B	6		PL81B	6	
AE37	PL67C	6		PL81C	6	
AF37	PL67D	6		PL81D	6	
AC41	PL68A	6		PL82A	6	
AD41	PL68B	6		PL82B	6	
AE34	PL68C	6		PL82C	6	
AF34	PL68D	6		PL82D	6	
AC42	PL69A	6		PL83A	6	
AD42	PL69B	6		PL83B	6	
AE33	PL69C	6		PL83C	6	
AF33	PL69D	6		PL83D	6	
AE38	PL72A	6		PL86A	6	
AF38	PL72B	6		PL86B	6	
AE32	PL72C	6		PL86C	6	
AF32	PL72D	6		PL86D	6	
AE41	PL73A	6		PL87A	6	
AF41	PL73B	6		PL87B	6	
AE31	PL73C	6		PL87C	6	
AF31	PL73D	6		PL87D	6	
AE42	PL74A	6		PL88A	6	
AF42	PL74B	6		PL88B	6	
AG37	PL74C	6		PL88C	6	
AH37	PL74D	6		PL88D	6	



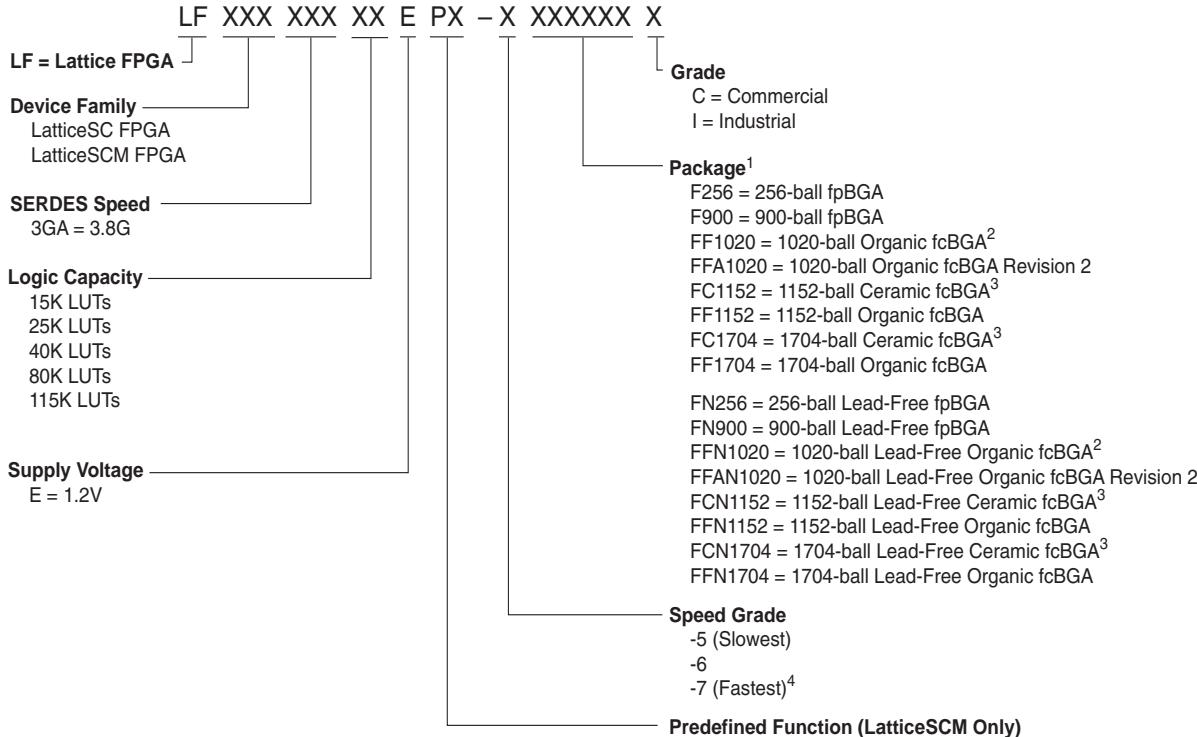
**LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA<sup>1,2</sup> (Cont.)**

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

January 2010

Data Sheet DS1004

### Part Number Description



1. fpBGA = 1.0 mm pitch BGA, fcBGA = 1.0 mm flip-chip BGA (organic and ceramic).

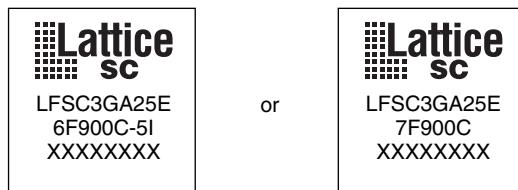
2. Converted to organic fcBGA per PCN #02A-10.

3. Converted to organic fcBGA per PCN #01A-10.

4. Not available in the LatticeSC115 and LatticeSCM115 devices.

### Ordering Information

Depending on the speed and temperature grade, the device can either be dual marked or single marked. The commercial grade is one speed grade faster than the associated dual marked industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:



Temperature Grade	Speed Grade	Single or Dual Mark?
Commercial	-7	Either OK
	-6	Dual Only
	-5	Single Only
Industrial	-6	Either OK
	-5	Dual Only

## Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152I <sup>1</sup>	-6	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-5FC1152I <sup>1</sup>	-5	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-6FC1704I <sup>1</sup>	-6	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-5FC1704I <sup>1</sup>	-5	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSC3GA115E-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152I <sup>1</sup>	-6	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FC1152I <sup>1</sup>	-5	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FC1704I <sup>1</sup>	-6	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FC1704I <sup>1</sup>	-5	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

